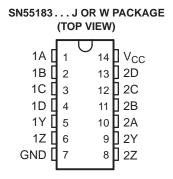


www.ti.com SLLS932-JULY 2008

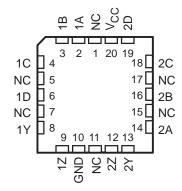
# RAD-TOLERANT CLASS V, DUAL DIFFERENTIAL LINE DRIVER

#### **FEATURES**

- Single 5-V Supply
- Differential Line Operation
- Dual Channels
- TTL Compatibility
- Short-Circuit Protection of Outputs
- Output Clamp Diodes to Terminate Line Transients
- High-Current Outputs
- Quad Inputs
- Single-Ended or Differential AND/NAND Outputs
- Designed for Use With Dual Differential Drivers SN55182 and SN75182
- Designed to Be Interchangeable With National Semiconductor DS7830 and DS8830
- Rad-Tolerant: >40 KRad(Si) TID
- QML-V Qualified, SMD 5962-79008







NC - No internal connection

#### **DESCRIPTION**

The SN55183 dual differential line driver is designed to provide differential output signals with high current capability for driving balanced lines, such as twisted pair, at normal line impedances without high power dissipation. The device can be used as a TTL expander/phase splitter, because the output stages are similar to TTL totem-pole outputs.

The driver is of monolithic single-chip construction, and both halves of the dual circuits use common power supply and ground terminals.

The SN55183 is characterized for operation over the full military temperature range of -55°C to 125°C.

#### PACKAGING/ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-55°C to 125°C	J package	5962-7900801VCA	5962-7900801VCA
-55 C to 125 C	W package	5962-7900801VDA	5962-7900801VDA

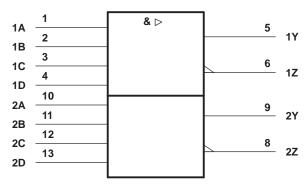
- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.
- (2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

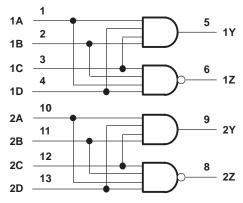


# Logic Symbol<sup>†</sup>



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# **Logic Diagram (Positive Logic)**



Positive logic: y = ABCD,  $Z = \overline{ABCD}$ 

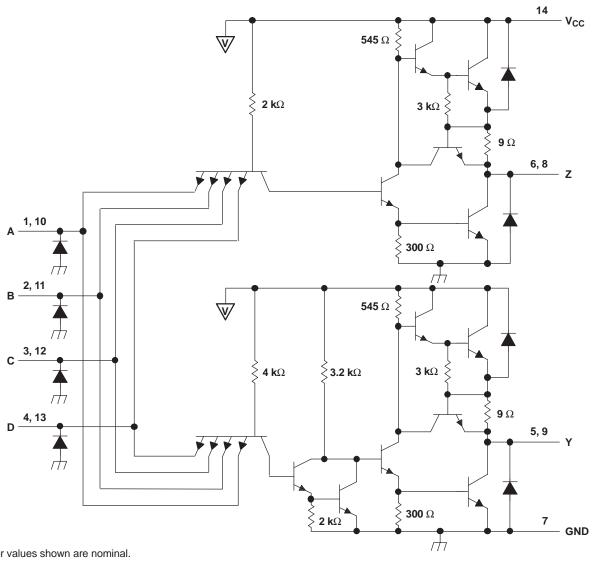
Pin numbers shown are for the J and W packages.

Pin numbers shown are for the J and W packages.



www.ti.com SLLS932-JULY 2008

## Schematic (Each Driver)



Resistor values shown are nominal.

Pin numbers shown are for the J and W packages.

# ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage (2)		7	V	
VI	Input voltage		5.5	V	
	Duration of output short circuit (3)		1	S	
	Continuous total power dissipation	See Dissipa	ation Ratin	gs Table	
T <sub>stg</sub>	Storage temperature range	-65	150	°C	
	Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	J or W package		300	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

All voltage values, except differential voltages, are with respect to network ground terminal.

Not more than one output should be shorted to ground at any one time.



## **DISSIPATION RATINGS**

PACKAGE <sup>(1)</sup>	T <sub>A</sub> ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING	
J	1375 mW	11.0 mW/°C	880 mW	275 mW	
W	1000 mW	8.0 mW/°C	640 mW	200 mW	

<sup>(1)</sup> SN55183 chips are alloy mounted.

## **RECOMMENDED OPERATING CONDITIONS**

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			V
$V_{IL}$	Low-level input voltage			0.8	V
I <sub>OH</sub>	High-level output current			-40	mA
I <sub>OL</sub>	Low-level output current			40	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	°C



www.ti.com SLLS932-JULY 2008

## **ELECTRICAL CHARACTERISTICS**

over recommended ranges of V<sub>CC</sub> and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST C	TEST CONDITIONS			TYP <sup>(1)</sup>	MAX	UNIT	
\/	Lligh lovel output voltage	Y (AND)	V 2.V	$I_{OH} = -0.8 \text{ mA}$		2.4			V	
V <sub>OH</sub>	High-level output voltage	outputs	$V_{IH} = 2 V$	$I_{OH} = -40 \text{ mA}$		1.8	3.3		V	
\/	Low-level output voltage	Y (AND)	V <sub>IL</sub> = 0.8 V	$I_{OL} = 32 \text{ mA}$			0.2		V	
V <sub>OL</sub>	Low-level output voltage	outputs		$I_{OL} = 40 \text{ mA}$			0.22	0.4		
\/	High lovel output voltage	Z (NAND)	V <sub>IL</sub> = 0.8 V	$I_{OH} = -0.8 \text{ mA}$		2.4			V	
V <sub>OH</sub>	High-level output voltage	outputs		$I_{OH} = -40 \text{ mA}$		1.8	3.3			
\/	and level and and relations	Z (NAND)	V <sub>IH</sub> = 2 V	I <sub>OL</sub> = 32 mA			0.2		V	
V <sub>OL</sub>	Low-level output voltage	outputs		$I_{OL} = 40 \text{ mA}$			0.22	0.4	V	
I <sub>IH</sub>	High-level input current		V <sub>IH</sub> = 2.4 V					120	μΑ	
I	Input current at maximum input voltage		V <sub>IH</sub> = 5.5 V					2	mA	
I <sub>IL</sub>	Low-level input current		V <sub>IL</sub> = 0.4 V					-4.8	mA	
Ios	Short-circuit output current (2)		$V_{CC} = 5 V$ ,	T <sub>A</sub> =125°C <sup>(3)</sup>		-40	-100	-120	mA	
I <sub>CC</sub>	Supply current (average per driver)		V <sub>CC</sub> = 5 V,	All inputs at 5 V,	No load		10	18	mA	

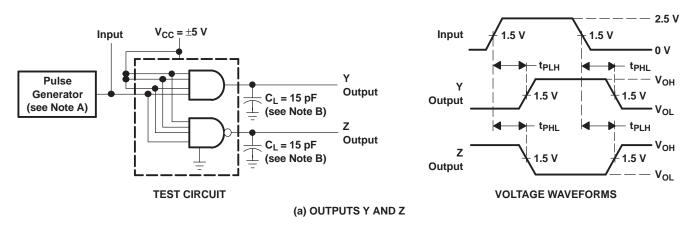
# **SWITCHING CHARACTERISTICS**

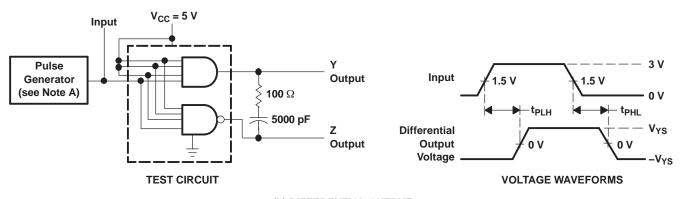
 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ 

	PARAMETER	TES	T CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>PLH</sub>	Propagation delay time, low- to high-level Y output	AND gates	C <sub>L</sub> = 15 pF, See Flgure 1(a)		8	12	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level Y output	AND gates	C <sub>L</sub> = 15 pF, See Flgure 1(a)		12	18	ns
t <sub>PLH</sub>	Propagation delay time, low- to high-level Z output	NAND gates	C <sub>L</sub> = 15 pF, See Figure 1(a)		6	12	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level Z output	NAND gates	C <sub>L</sub> = 15 pF, See FIgure 1(a)		6	8	ns
t <sub>PLH</sub>	Propagation delay time, low- to high-level differential output	$R_L = 100 \Omega i$	Y output with respect to Z output, $R_L = 100 \Omega$ in series with 5000 pF, See Figure 1(b)		9	16	ns
t <sub>PHL</sub>	Propagation delay time, high- to low-level differential output	Y output with $R_L = 100 \Omega$ is See Figure 1		8	16	ns	

 <sup>(1)</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.
 (2) Not more than one output should be shorted to ground at a time, and duration of the short circuit should not exceed one second.
 (3) T<sub>A</sub> = 125°C is applicable to SN55183 only.

#### PARAMETER MEASUREMENT INFORMATION





(b) DIFFERENTIAL OUTPUT

NOTES: A. The pulse generators have the following characteristics:  $Z_0$  = 50  $\Omega$ ,  $t_r \le$  10 ns,  $t_w$  = 0.5  $\mu$ s, PRR  $\le$  1 MHz.

- B. C<sub>L</sub> includes probe and jig capacitance.
- C. Waveforms are monitored on an oscilloscope with  $r_i \geq 1$  M  $\!\Omega_{\!\scriptscriptstyle L}$

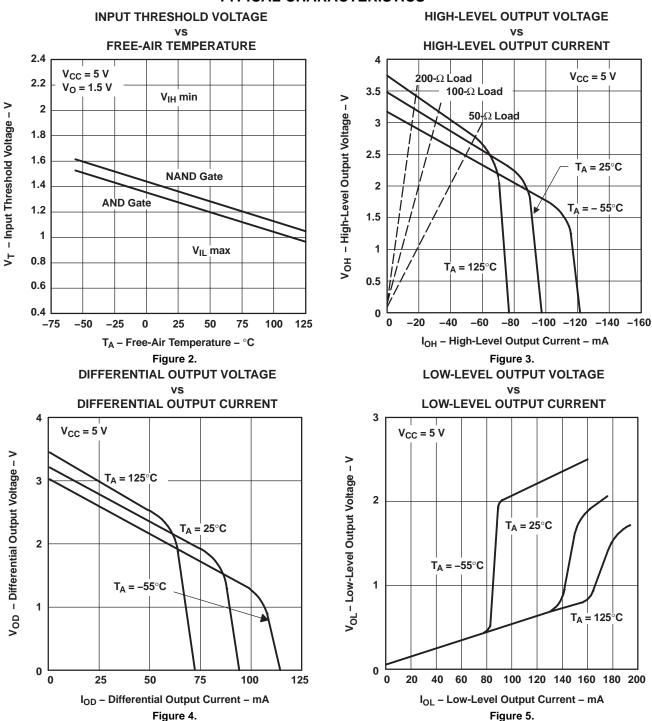
Figure 1. Test Circuits and Voltage Waveforms

Submit Documentation Feedback



www.ti.com SLLS932-JULY 2008

#### TYPICAL CHARACTERISTICS(1)

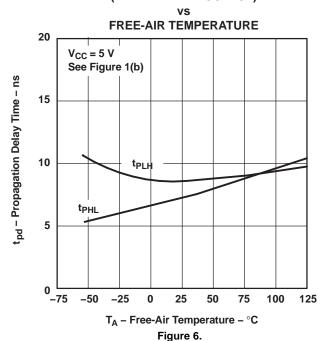


<sup>(1)</sup> Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

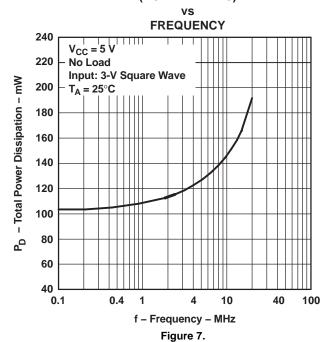


# TYPICAL CHARACTERISTICS<sup>(2)</sup> (continued)

# PROPAGATION DELAY TIME (DIFFERENTIAL OUTPUT)

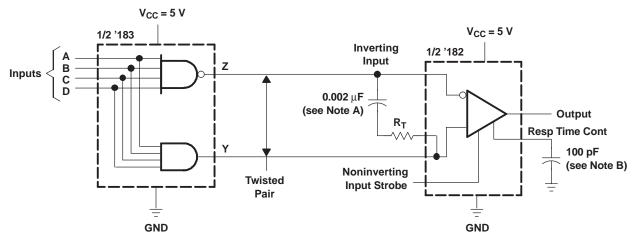


# TOTAL POWER DISSIPATION (BOTH DRIVERS)



www.ti.com SLLS932-JULY 2008

#### **APPLICATION INFORMATION**



NOTES: A. When the inputs are open circuited, the output is high. A capacitor may be used for dc isolation of the line-terminating resistor. At the frequency of operation, the impedance of the capacitor should be relatively small.

$$\begin{split} &\text{Example: let} \quad &f=5 \text{ MHz} \\ &C=0.002 \text{ } \mu F \\ &Z_{\text{(circuit)}} = \frac{1}{2\pi f C} = \frac{1}{2\pi (5\times 10^6)(0.002\times 10^{-6})} \\ &Z_{\text{(circuit)}} \approx 16\Omega \end{split}$$

B. Use of a capacitor to control response time is optional.

Figure 8. Transmission of Digital Data Over Twisted-Pair Line



www.ti.com 2-Dec-2023

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7900901VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7900901VC A SNV55183J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

# **PACKAGE OPTION ADDENDUM**

www.ti.com 2-Dec-2023

#### OTHER QUALIFIED VERSIONS OF SN55183-SP:

• Catalog : SN55183

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



#### NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
  Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
  Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2023, Texas Instruments Incorporated